



PolyZen Devices

Polymer Protected Zener Diode

PolyZen devices are polymer enhanced precision Zener diode micro-assemblies that help protect sensitive electronics from damage caused by inductive voltage spikes, voltage transients, incorrect power supplies and reverse bias.

The PolyZen micro-assembly incorporates a stable Zener diode for precise voltage clamping and a resistively non-linear, polymeric positive temperature coefficient (PPTC) layer that responds to either diode heating or overcurrent events by transitioning from a low to high resistance state.

PolyZen devices help provide resettable protection against damage caused by multi-watt fault events and require only 0.7W power dissipation. In the event of sustained high power conditions, the PPTC element of the device “trips” to limit current and generate voltage drop. This functionality helps protect both the Zener and the follow-on electronics, effectively increasing the diode's power handling capacity.



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Benefits

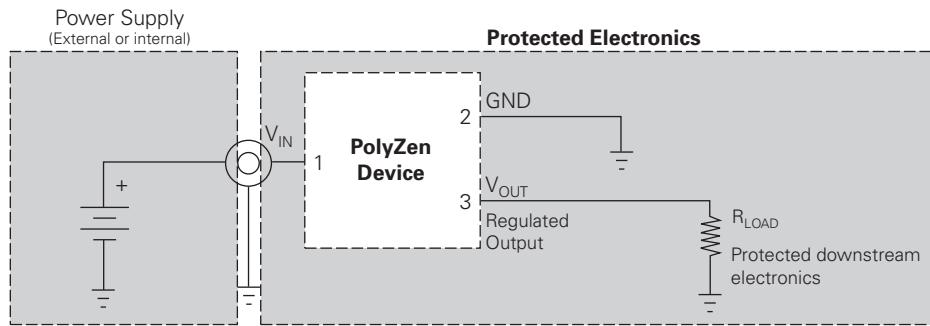
- Helps shield downstream electronics from overvoltage and reverse bias
- Trip events shut out overvoltage and reverse bias sources
- Analog nature of trip events minimize upstream inductive spikes
- Helps reduce design costs with single component placement and minimal heat sinking requirements

Features

- RoHS compliant
- Overvoltage transient suppression
- Hold currents up to 2.3A
- Time delayed, overvoltage trip
- Time delayed, reverse bias trip
- Power handling on the order of 30 watts
- Integrated device construction

Applications

- Portable media players
- Global positioning systems
- Hard disk drive 5V & 12V bus
- Automotive peripheral input power
- DC power port protection
- Industrial handheld POS

Figure PZ1 Typical Application Block Diagram for PolyZen Devices


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Table PZ1 Electrical Characteristics for PolyZen Devices

(Performance ratings @ 25°C unless otherwise specified)

Part Number	$V_Z(V)$			I_{Zt} (A)	I_{HOLD} @ 20°C (A)	R_{Typ} (Ω)	R_{1MAX} (Ω)	$V_{INT\ MAX}$		$I_{FLT\ MAX}$		
	Min.	Typ.	Max.					$V_{INT\ MAX}$ (V)	Test Current (A)	$I_{FLT\ MAX}$ (A)	Test Voltage (V)	
ZEN056V130A24LS	5.45	5.6	5.75	0.1	1.3	0.12	0.16	24V	3A	+10/-40	+24/-16V	
ZEN065V130A24LS	6.35	6.5	6.65	0.1	1.3	0.12	0.16	24V	3A	+6/-40	+24/-16V	
Coming* Soon	ZEN098V130A24LS	9.60	9.8	10.00	0.1	1.3	0.12	0.16	24V	3A	TBD/-40	+24/-16V
ZEN132V130A24LS	13.20	13.4	13.60	0.1	1.3	0.12	0.16	24V	3A	+2/-40	+24/-16V	
ZEN164V130A24LS	16.10	16.4	16.60	0.1	1.3	0.12	0.16	24V	3A	+1.25/-40	+24/-16V	
ZEN056V230A16LS	5.45	5.6	5.75	0.1	2.3	0.04	0.06	16V	5A	+5/-40	+16/-12V	
ZEN065V230A16LS	6.35	6.5	6.65	0.1	2.3	0.04	0.06	16V	5A	+3.5/-40	+16/-12V	
NEW	ZEN132V230A16LS	13.20	13.4	13.60	0.1	2.3	0.04	0.06	16V	5A	+2/-40	+20/-12V
Coming* Soon	ZEN056V075A48LS	5.45	5.6	5.75	0.1	0.75	0.28	0.45	48V	3A	+10/-40	+48/-16V
NEW	ZEN132V075A48LM	13.20	13.4	13.60	0.1	0.75	0.28	0.45	48V	3A	+2/-40	+48/-16V

* Data is preliminary

Table PZ2 Definition of Terms for PolyZen Devices

V_Z	Zener clamping voltage measured at current I_{Zt} and 20°C.
I_{Zt}	Test current at which V_Z is measured.
I_{HOLD}	Maximum steady state current I_{PTC} that will not generate a trip event at the specified temperature. Ratings assume $I_{FLT} = 0A$.
R_{Typ}	Typical resistance between V_{IN} and V_{OUT} pins when the device is at room temperature.
R_{1MAX}	The maximum resistance between V_{IN} and V_{OUT} pins, at room temperature, one hour after first trip or after reflow soldering.
I_{FLT}	Current flowing through the Zener diode.
$I_{FLT\ MAX}$	Maximum RMS fault current the Zener diode component of the device can withstand and remain resettable; testing is conducted at rated voltage with no load connected to V_{OUT} .
$V_{INT\ MAX}$	The voltage ($V_{IN} - V_{OUT}$ "post trip") at which typical qualification devices (98% devices, 95% confidence) survived at least 100 trip cycles and 24 hours trip endurance when "tripped" at the specified voltage and current (I_{PTC}).
Trip Event	A condition where the PPTC transitions to a high resistance state, thereby limiting I_{PTC} , and significantly increasing the voltage drop between V_{IN} and V_{OUT} .

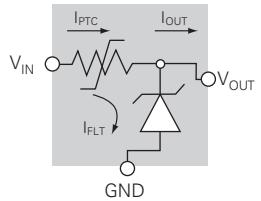
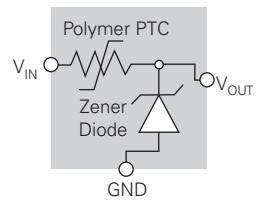


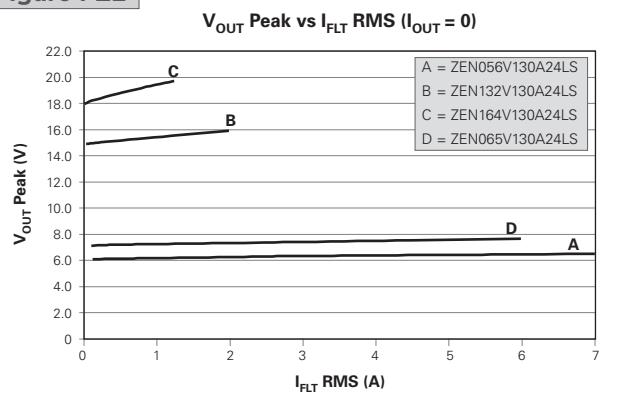
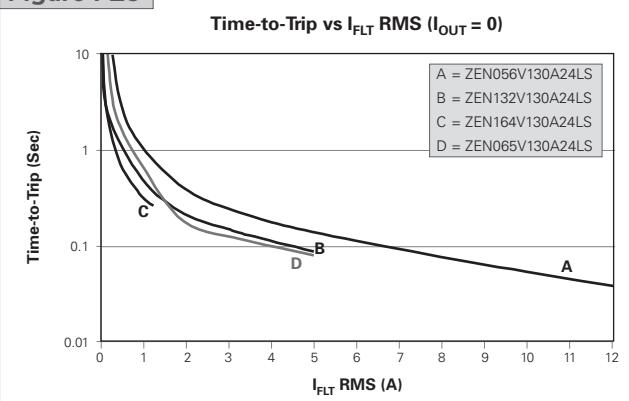
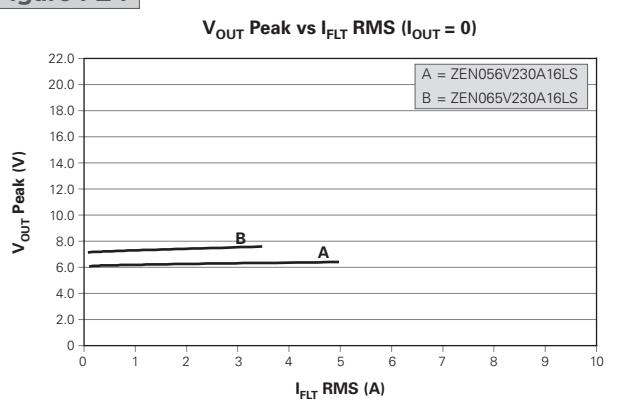
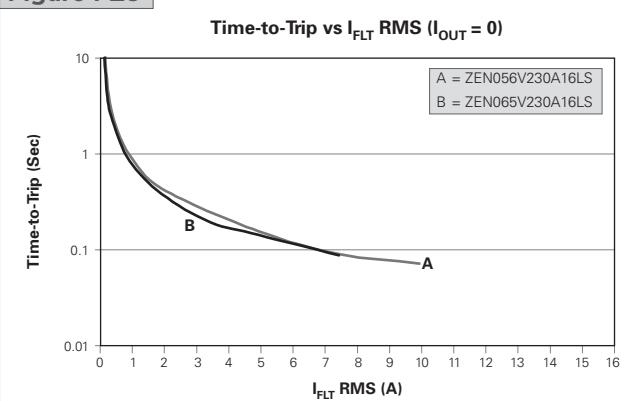
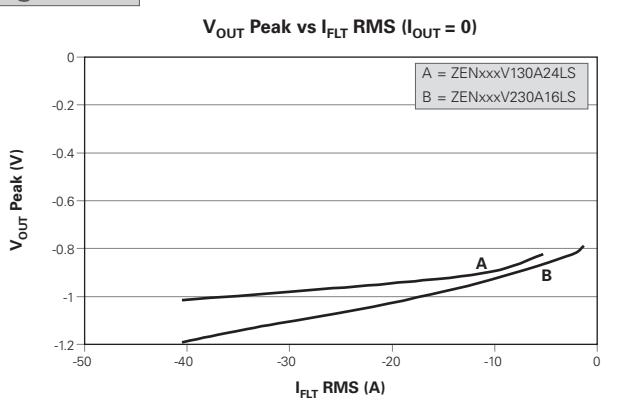
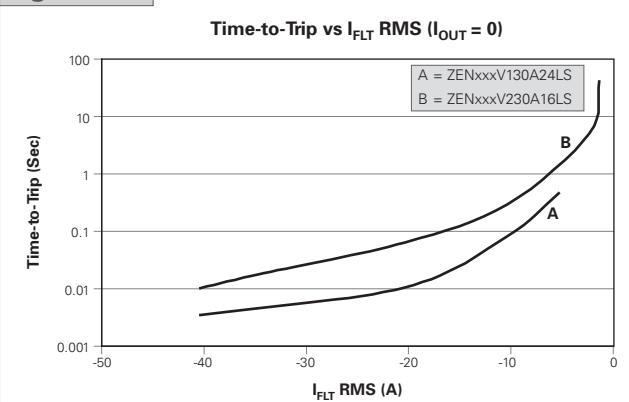
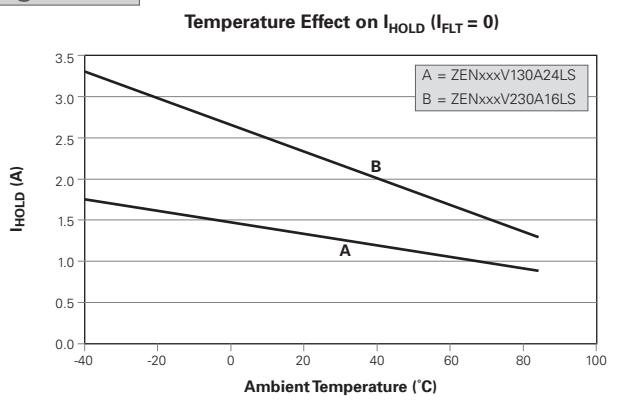
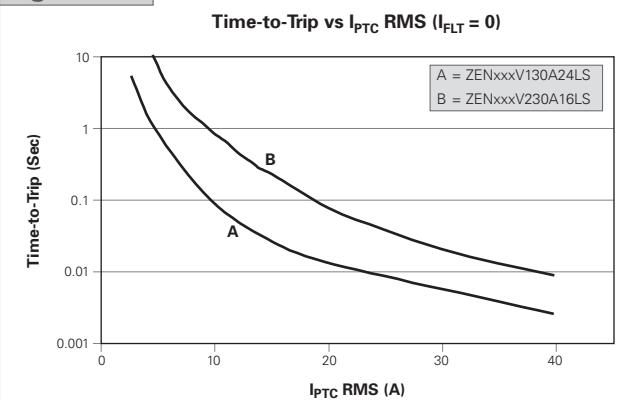
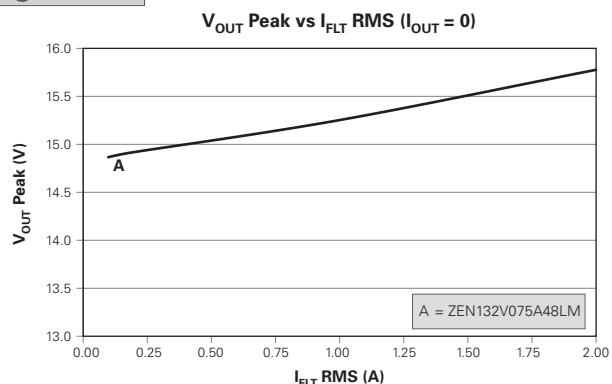
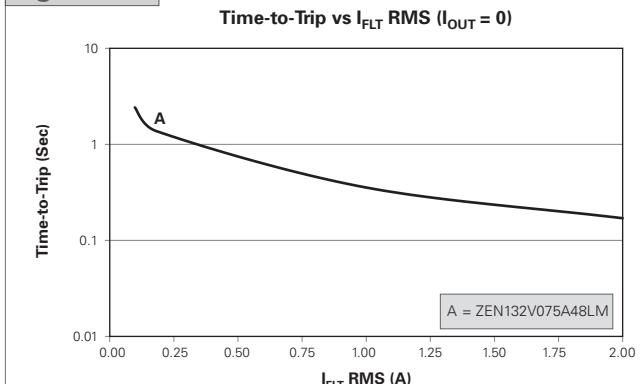
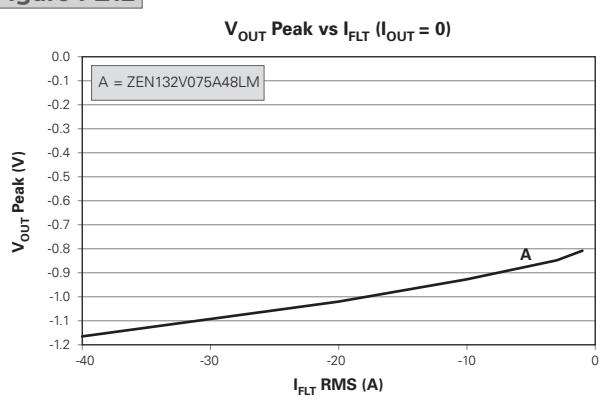
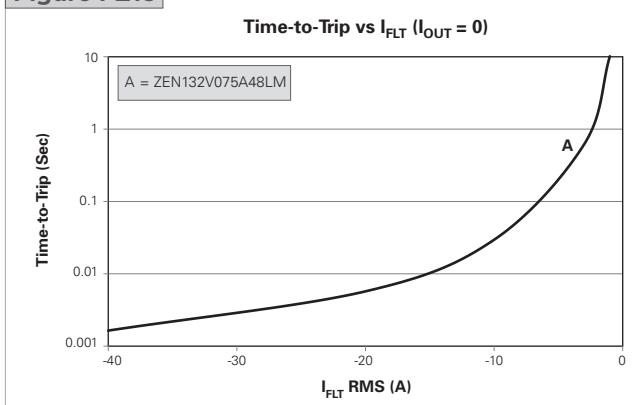
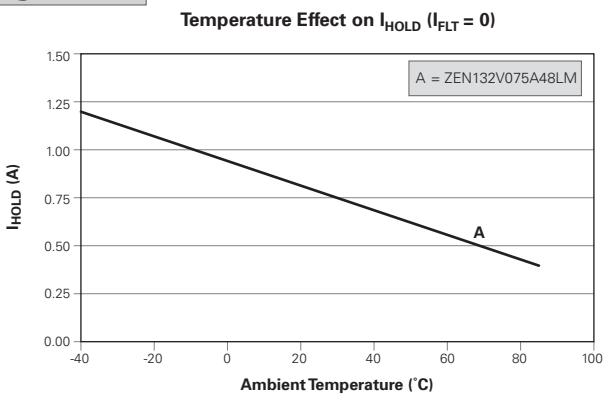
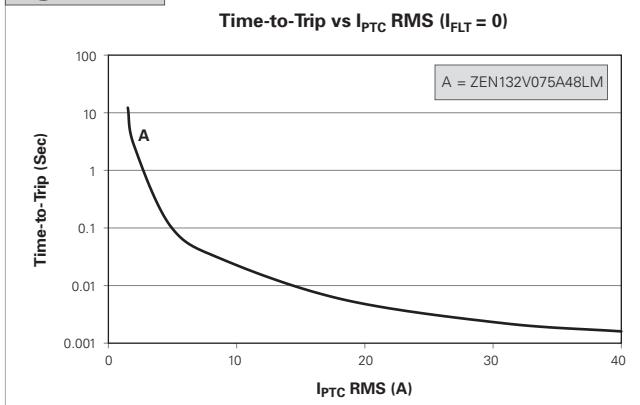
Figure PZ2-PZ15 Typical Performance Curves for PolyZen Devices
Figure PZ2

Figure PZ3

Figure PZ4

Figure PZ5

Figure PZ6

Figure PZ7

Figure PZ8

Figure PZ9


Figure PZ2-PZ15 Typical Performance Curves for PolyZen Devices

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Figure PZ10

Figure PZ11

Figure PZ12

Figure PZ13

Figure PZ14

Figure PZ15

Table PZ3 General Characteristics for PolyZen Devices

Operating temperature range	-40° to +85°C	
Storage temperature	-40° to +85°C	
ESD withstand	15kV	Human body model
Diode capacitance	4200pF	Typical @ 1MHz, 1V RMS
Construction	RoHS compliant	

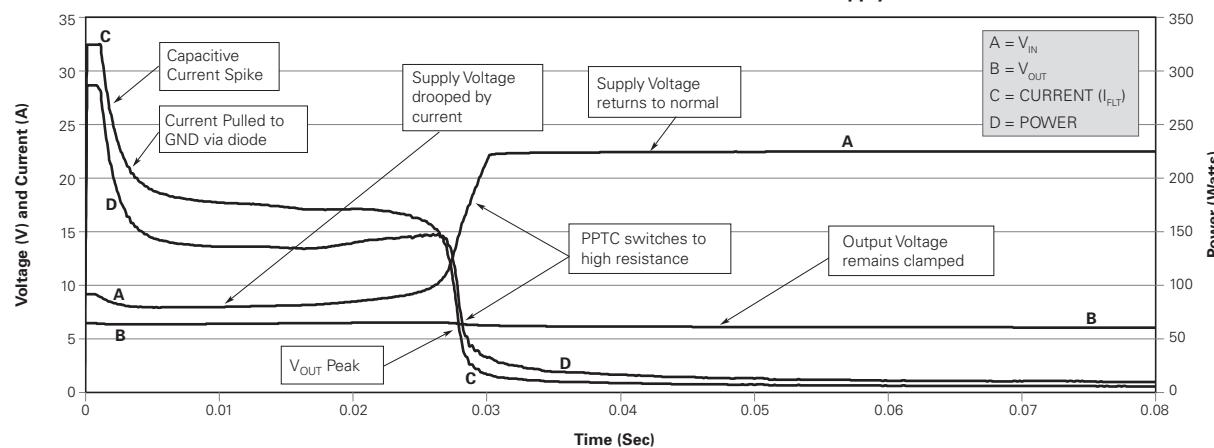
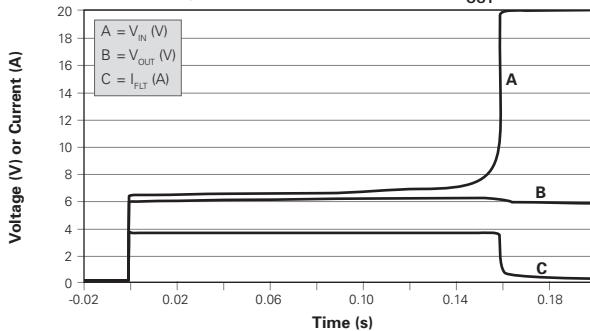
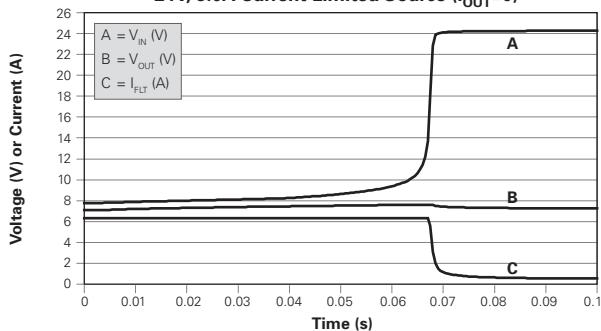
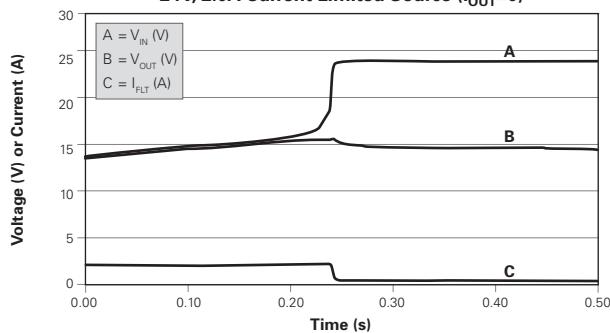
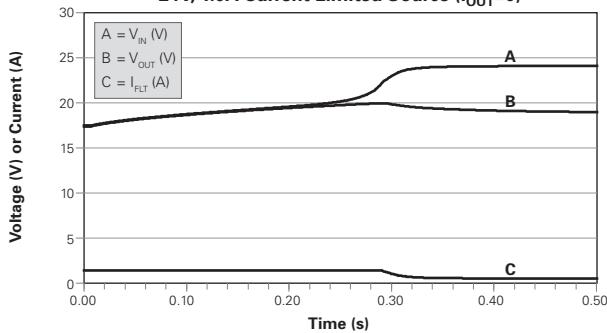
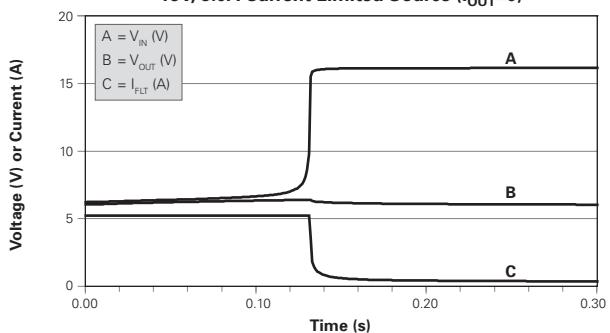
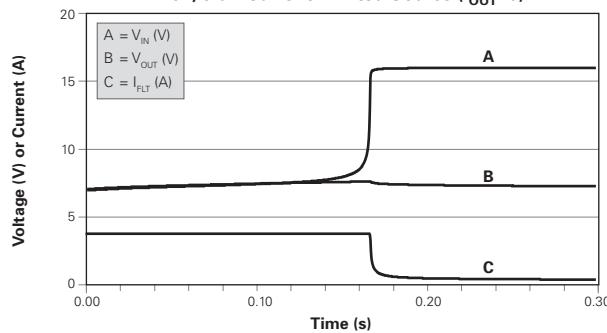
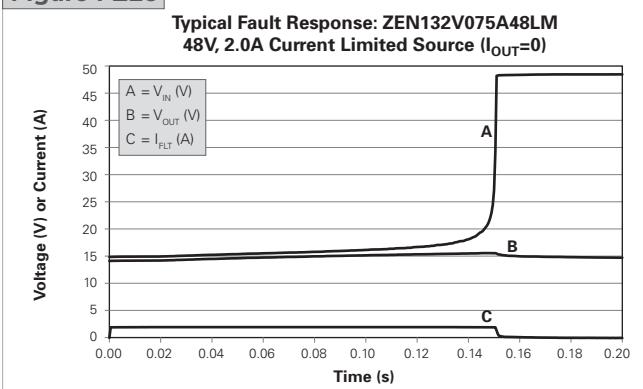
Figure PZ16-PZ23 Basic Operation Examples for PolyZen Devices
Figure PZ16
**Hot-Plug Response
ZEN056V130A24LS vs a 22V/120W Universal Power Supply**

Figure PZ17
**Typical Fault Response: ZEN056V130A24LS
24V, 3.5A Current Limited Source ($I_{OUT}=0$)**

Figure PZ18
**Typical Fault Response: ZEN065V130A24LS
24V, 5.0A Current Limited Source ($I_{OUT}=0$)**

Figure PZ19
**Typical Fault Response: ZEN132V130A24LS
24V, 2.0A Current Limited Source ($I_{OUT}=0$)**

Figure PZ20
**Typical Fault Response: ZEN164V130A24LS
24V, 1.0A Current Limited Source ($I_{OUT}=0$)**

Figure PZ21
**Typical Fault Response: ZEN056V230A16LS
16V, 5.0A Current Limited Source ($I_{OUT}=0$)**

Figure PZ22
**Typical Fault Response: ZEN065V230A16LS
16V, 3.5A Current Limited Source ($I_{OUT}=0$)**


Figure PZ16-PZ23 Basic Operation Examples for PolyZen Devices

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Figure PZ23


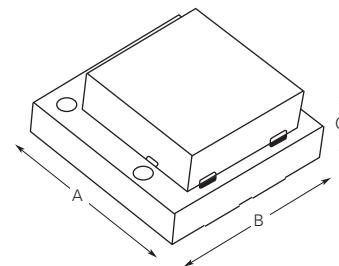
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Table PZ4 Packaging and Marking Information for PolyZen Devices

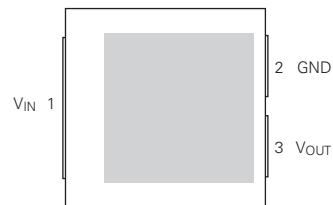
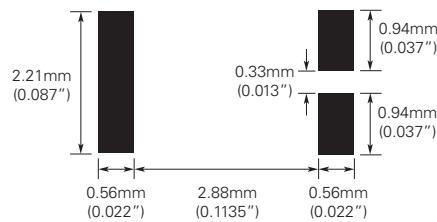
Part Number	Bag Quantity	Tape & Reel Quantity	Standard Package
ZENxxxxVyyyAzzLS	-	3,000	15,000

Table PZ5 Dimensions for PolyZen Devices in Millimeters (Inches)

	A		B		C	
	Min.	Max.	Min.	Max.	Min.	Max.
mm	3.85	4.15	3.85	4.15	1.4	2.0
inch	(0.150)	(0.163)	(0.152)	(0.163)	(0.060)	(0.081)


Table PZ6 Pad Layout and Configuration Information for PolyZen Devices

Pin Number	Pin Name	Pin Function
1	V_{IN}	V_{IN} = Protected input to Zener diode
2	GND	GND = Ground
3	V_{OUT}	V_{OUT} = Zener regulated voltage output

**Pin Configuration
(Top View)**

Pad Dimensions


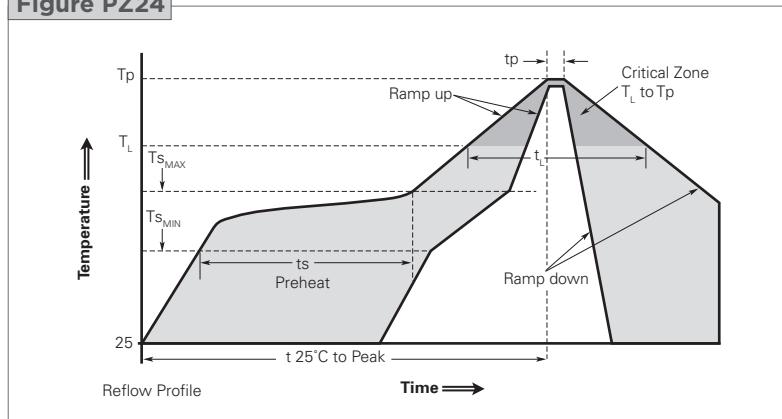
Solder Reflow and Rework Recommendation for PolyZen Devices

Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average ramp up rate ($T_{s_{MAX}}$ to T_p)	3°C/second max.
Preheat	
• Temperature min. ($T_{s_{MIN}}$)	150°C
• Temperature max. ($T_{s_{MAX}}$)	200°C
• Time ($t_{s_{MIN}}$ to $t_{s_{MAX}}$)	60-180 seconds
Time maintained above:	
• Temperature (T_L)	217°C
• Time (t_L)	60-150 seconds
Peak/Classification temperature (T_p)	260°C
Time within 5°C of actual peak temperature	
Time (t_p)	20-40 seconds
Ramp down rate	6°C/second max.
Time 25°C to peak temperature	8 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface.

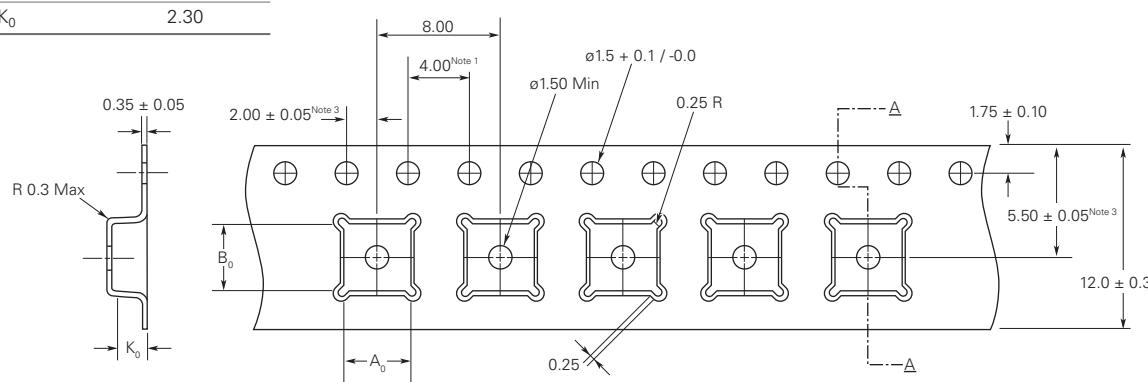
Figure PZ24



Tape and Reel Specifications for PolyZen Devices (in Millimeters)

Figure PZ25 | EIA Referenced Taped Component Dimensions for PolyZen Devices (in Millimeters)

Description	Dimension (mm)
A_0	4.35
B_0	4.35
K_0	2.30

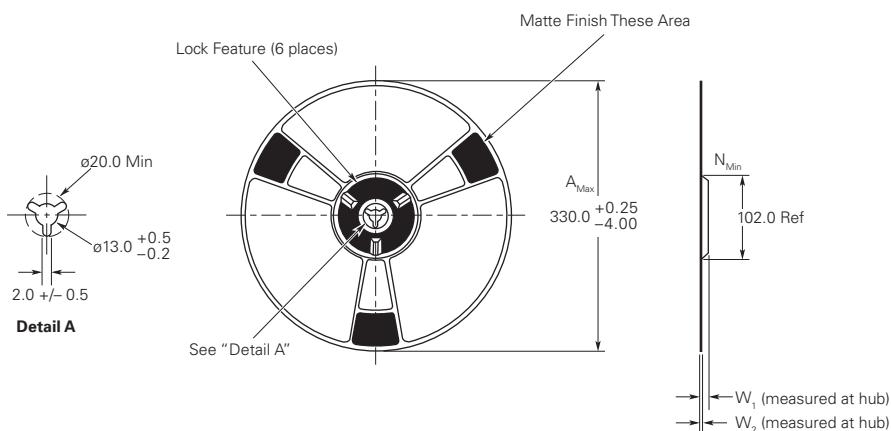


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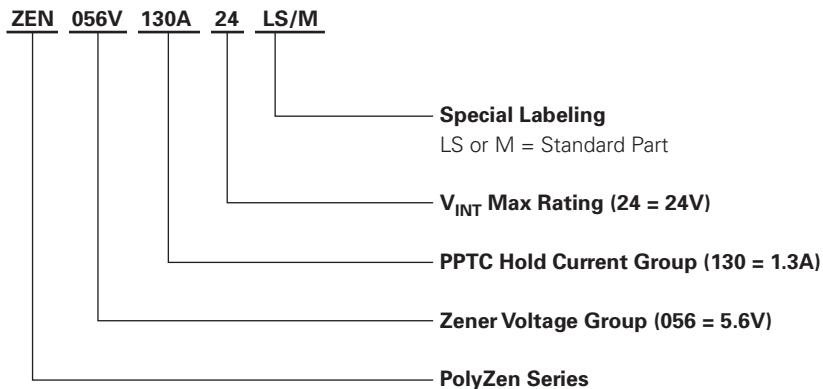
1. 10 sprocket hole pitch cumulative tolerance ± 0.2
2. Camber in compliance with EIA 481
3. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole

Figure PZ26 | Reel Dimensions for PolyZen Devices (in Millimeters)

Description	Dimension (mm)
A _{Max}	330
N _{Min}	102
W ₁	8.4
W ₂	11.1



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Part Numbering System for PolyZen Devices

⚠ Warning :

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